

Ultrafast High Voltage Kicker System Hardware for Ion Clearing Gaps

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RadiaBeam



- Founded in 2004
- ~50 employees and growing
- 30,000 ft² headquarters in Santa Monica, CA



 Accelerator R&D, design, engineering, manufacturing and testing all under one roof in a dynamic, small-business setting



Tour: Machine Shop



- Multiple CNC milling and turning centers, > \$3 million investment
- Dedicated "clean shop" for RF and UHV machining
- Full-suite of inspection equipment, including CMM
- 10 highly-skilled machinists
- ISO 9001 compliant quality system







Project Goals and Specs

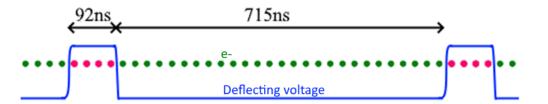


The ionization scattering of the electron beam with residual gas molecules causes ion trapping in the electron rings, both in the collider and electron cooling system. The trapped ions may cause emittance growth, tune shift, halo formation, and coherent coupled bunch instabilities. Therefore, the beam temporal structure needs gaps to clear the ions to prevent them from accumulating turn after turn. Typically, the gap in the bunch train has a length of a few percent of the ring circumference.

A fast deflector (kicker) is needed for EIC ERL cooler to form a ~100ns gap at ~1MHz (37.5MHz, ultimately 98.5MHz microbunches)

Most recently 200ns at 470KHz

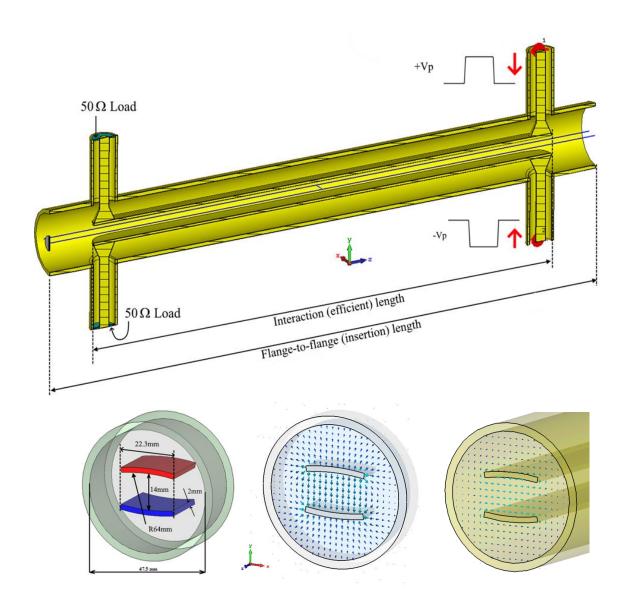
- Stripline kicker is a practical solution for such need
- RadiaBeam is building a kicker and twochannel pulsed power source intended to be installed and tested at Jefferson Lab
 - Aperture 14 mm
 - Maximum insertion length 75cm



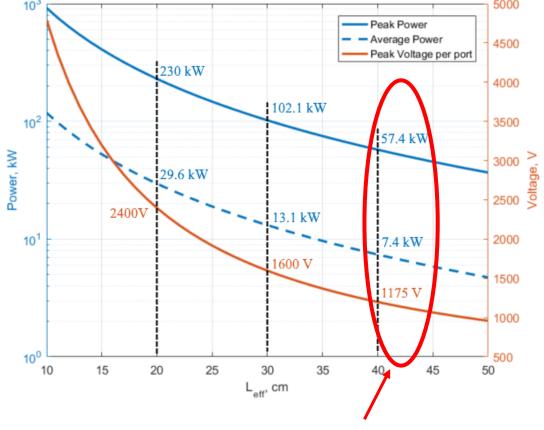
| Parameter | Value |
|---------------------------|---|
| Deflecting angle | 20 mrad (deflecting voltage 140 kV) |
| Electron Beam Energy | 7 MeV |
| Bunch Repetition Rate | 37.5 MHz |
| Bunch rms transverse size | σ=1 mm |
| Deflecting Pulse Width | 100 ns flat-top required to deflect 4 out of 31 bunches in train |
| Kicker operation per rate | 1.4 MHz (715ns between the pulses) |
| Rise + Fall Time | <20 ns (10ns desired) |
| Aperture (gap) | 14 mm |
| Required pulsed power | 27.6 kW peak power per channel (55.2 kW total); 3.8 kW average power per channel (7.6 kW total) |

EM design





Power required for 20mrad deflection

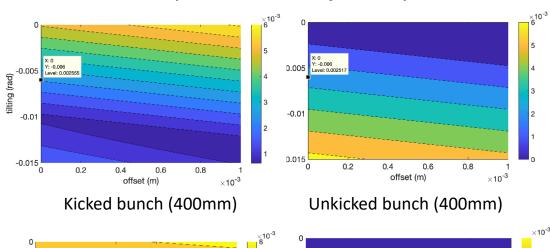


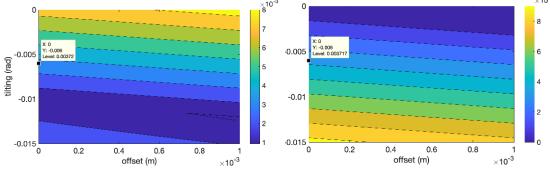
40cm interaction length

Beam dynamics study



Exit offset spectrum over injection parameters





Kicked bunch (600mm) Unkicked bunch (600mm)

Beam loss with various interaction lengths

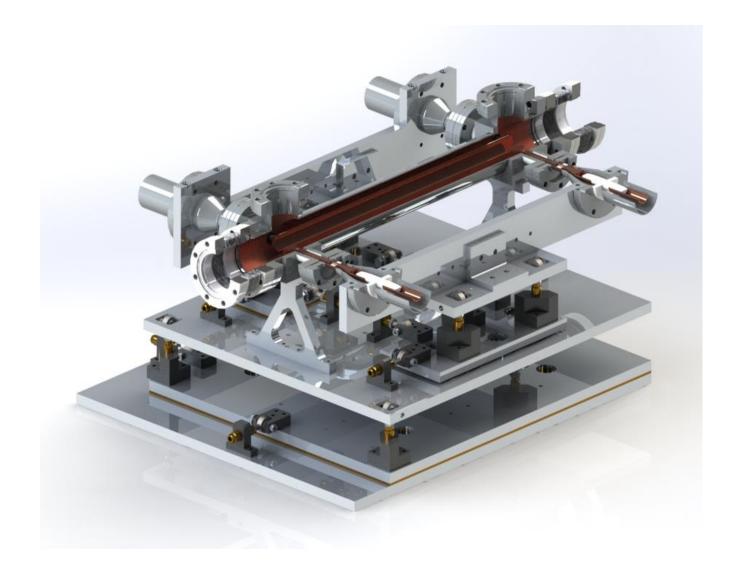
| Analytic evaluation | Case 1 | Case 2 | Case 3 | Case 4 | Case 5 | Case 6 | Case 7 | Case 8 |
|---------------------------------|--------------------|----------------------|----------------------|----------------------|-----------------------|-----------------------|----------------------|----------------------|
| 20 mrad Kick | yes | yes | yes | yes | yes | no | yes | no |
| $L_{\rm eff}$ (mm) | 200 | 300 | 400 | 600 | 400 | 400 | 600 | 600 |
| g(mm) | 14 | 14 | 14 | 14 | 14 | 14 | 14 | 14 |
| $V_{\rm p}\left({\sf V}\right)$ | 2275 | 1560 | 1175 | 790 | 1175 | 1175 | 790 | 790 |
| $Offset_i (mm)$ | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| Tilt _i (mm) | 0 | 0 | 0 | 0 | -5 | -5 | -6 | -6 |
| Beam loss (%) | 1×10^{-6} | 8.8×10^{-5} | 0.0027 | 0.21 | 5.4×10^{-5} | 4.7×10^{-5} | 4.6×10^{-3} | 4.8×10^{-3} |
| $P_b(W)$ LERF | 4×10^{-4} | 0.04 | 1.1 | 87.3 | 0.022 | 0.02 | 2 | 2 |
| $P_b(W)$ JLEIC | 0.04 | 3.4 | 104.5 | 8.1×10^{3} | 2.1 | 1.8 | 178 | 186 |
| P_{RF} (kW) | 14.5 | 6.8 | 3.85 | 1.75 | 3.85 | 3.85 | 1.75 | 1.75 |
| CST simulation | | | | | | | | |
| Beam loss (%) | 7×10^{-6} | 4×10^{-5} | 1.6×10^{-3} | 0.38 | 4.65×10^{-5} | 4.66×10^{-5} | 3.6×10^{-3} | 3.6×10^{-3} |
| $P_b(W)$ LERF | 0.003 | 0.02 | 0.66 | 158 | 0.02 | 0.02 | 1.5 | 1.5 |
| P_b (W) JLEIC | 0.27 | 1.55 | 62 | 1.47×10^{4} | 1.8 | 1.8 | 140 | 140 |
| Space charge | | | | | | | | |
| Beam loss (%) | - | | - | - | 1.8×10^{-3} | 4.7×10^{-5} | -, | - |
| $P_b(W)$ LERF | - | - | - | - | 0.7 | 0.02 | - | - |
| P_b (W) JLEIC | - | - | - | - | 70 | 1.8 | - | - |
| | | | | | | | | |

40cm interaction length

Engineering model



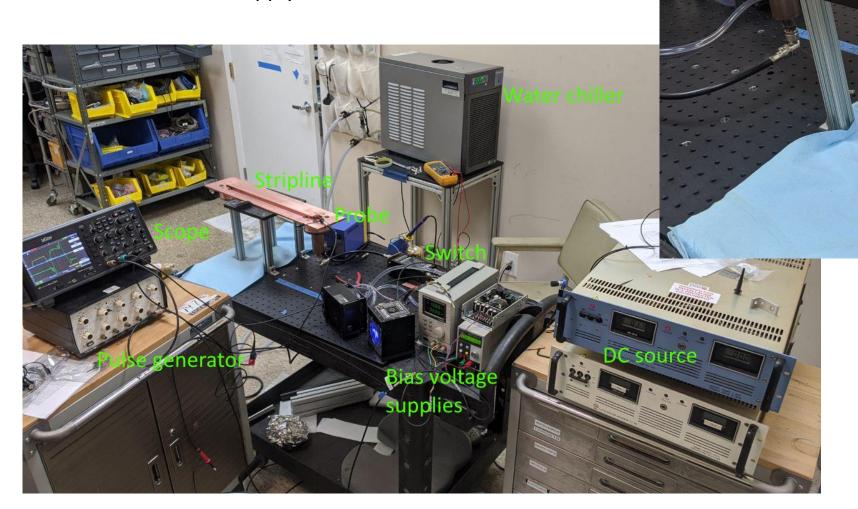
- Standard 1-5/8" EIA compatible
- XYZ Positioning stage
- No dielectric supports



Pulser testing setup



- 50cm-long 50 Ohm stripline, VSWR <1.1 from DC to 1 GHz
- Si MOSFET and GaN water-cooled high-power switches
- 2000 V / 10 A DC supply

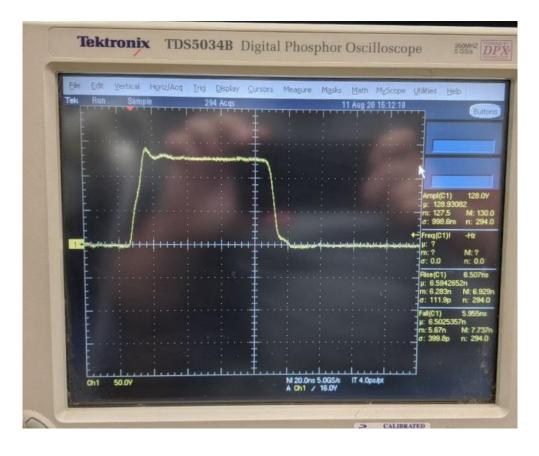


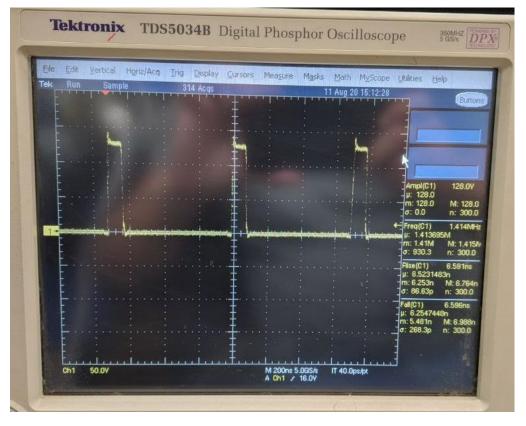
Pulser testing (Si MOSFET)



Achieved:

- 7ns rise and 6ns fall times at 100 ns flat-top with 87ps rms timing jitter
- Highly stable and controllable pulse length
- 1.4 MHz repetition rate
- 50% efficiency



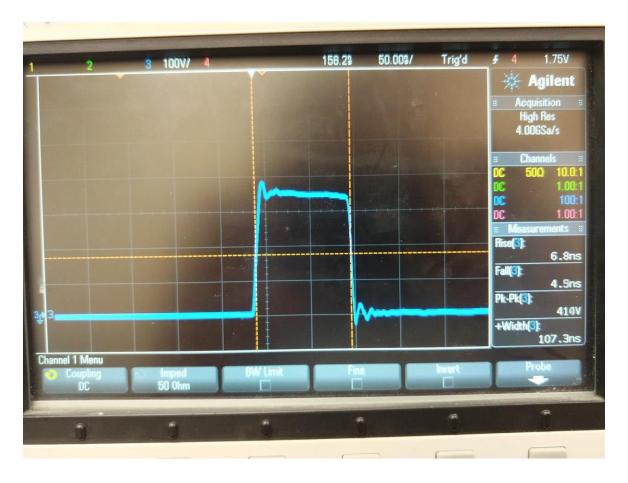


Pulser testing (Gallium Nitride)



Achieved:

- 6.8ns rise and 4.5ns fall times @ 107 ns flat-top with 100ps rms timing jitter
- Highly stable and controllable pulse length
- 1.4 MHz repetition rate
- 82% efficiency

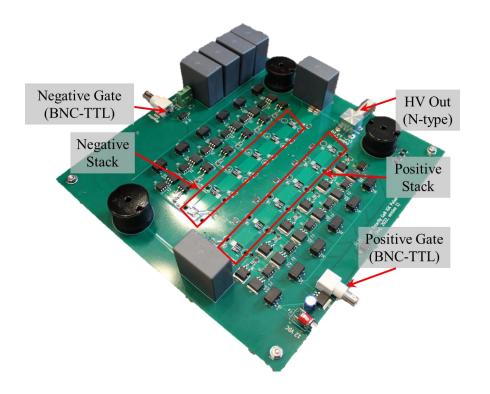


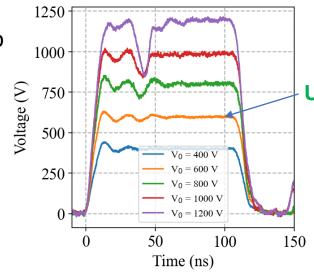
RadiaBeam pulser development (GaN) - 1



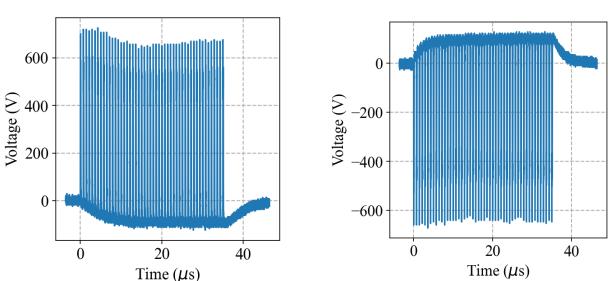
Achieved:

- 10 ns rise and 11 ns fall times @ 107 ns flat-top
- 1.4 MHz repetition rate (short bursts)
- 85% efficiency





Up to 600V so far (to be improved)



Positive channel Negative channel 1.4 MHz bursts

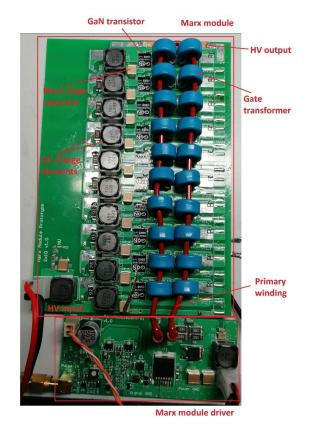
RadiaBeam pulser development (GaN)

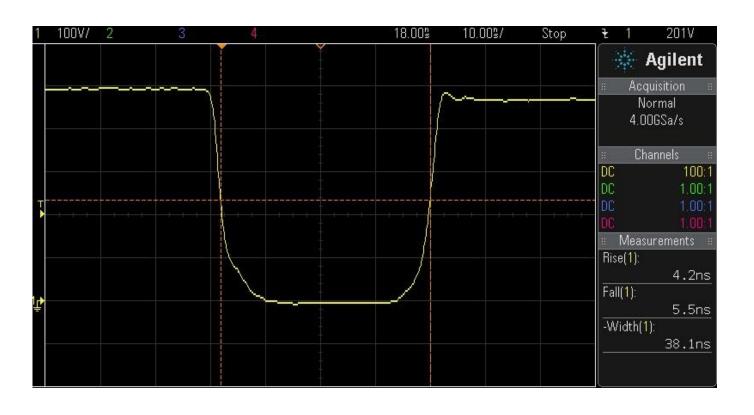


Achieved*:

- 4.2 ns rise and 5.5ns fall times @ 38 ns flat-top
- 100 Hz repetition rate
- 95% efficiency

*under Phase I project DE-SC0021548 2022 PHASE II for EIC pulser, **50kV** 7ns rise/fall (4.5ns – achieved in Phase I), 30ns * 100 Hz





Summary:



- Kicker EM and mechanical design are complete
- Improve GaN-based pulser to achieve 1175V, 5/6ns rise/fall, 1.4 MHz
- Assemble two-channel pulser
- Kicker fabrication, assembly and tests
- Installation and beam-based tests